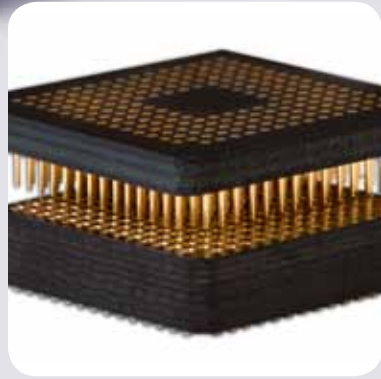


BGA Socket Adapter Systems



Features

- Soldering BGA Device to adapter subjects BGA to less thermal stress than soldering BGA directly to a PCB due to the adapter's lower mass.
- Uses same footprint as BGA device.
- Custom adapters available for heat sink attachment.
- Gold plated screw-machined terminals for superior durability.
- Unique SMT Adapter provides reliable solution for mounting or socketing LGA or re-worked BGA devices.
- SMT Adapters mate with our BGA Sockets for LGA to BGA conversion or SMT Board to Board applications.

Specifications



Terminals:
Brass - Copper Alloy (C36000)

Solder Ball:
Lead-free: 95.5Sn/4.0Ag/0.5Cu
Tin/Lead: 63Sn/37Pb

Plating:
G - Gold over Nickel

Ball Grid Array (BGA) Adapters 0.80mm, 1.00mm, and 1.27mm Pitch

Table of Models

	Description: Standard Adapter (A) Material: FR-4 Fiberglass Epoxy Board Note: Mates with Standard Socket (S)	Insulator Size: BGA device body +.079/(2.00)
	Description: Extraction Slot Adapter (AX) Material: FR-4 Fiberglass Epoxy Board Note: Mates with Extraction Socket (SB)	Insulator Size: BGA device body +.157/(4.00)

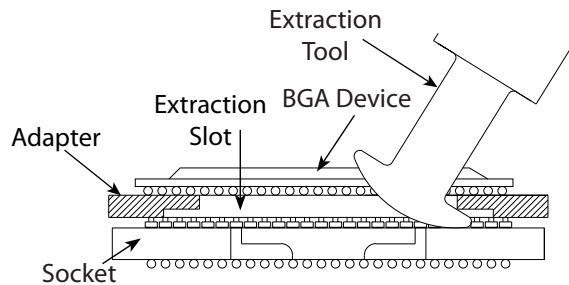
Note: For use with LGA or reworked BGA devices, select surface mount (SMT) terminals which feature solder balls on device side. SMT Adapter terminals may also be used for surface mount board to board applications.

Options

Extraction Tool

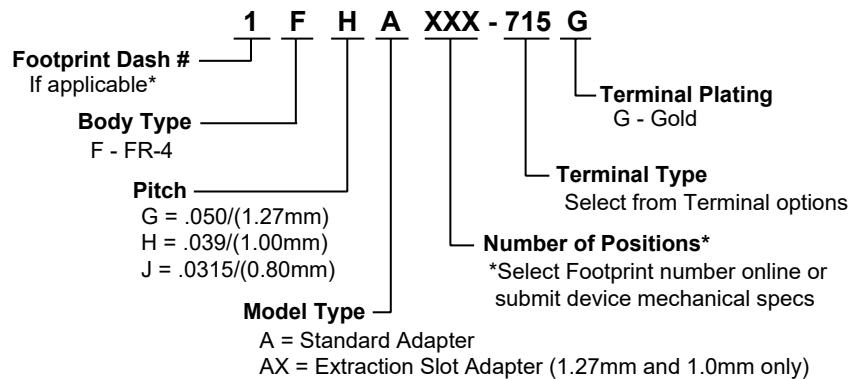


P/N 8125



- Insert "T" bar end of tool into extraction slot adapter.
- Slide tool to end of slot and pry adapter from socket.
- Repeat in additional slots until adapter is separated from socket.
- Works with Molded or FR-4 sockets.

How To Order



Consult factory for custom 0.75mm pitch designs.

For SMT Adapters, select Model Type A or AX and appropriate SMT Terminal Type from page 5.



Ball Grid Array (BGA) Adapters

For use with mating BGA Adapter Sockets

BGA Socket Adapter Systems

Standard Terminals

Consult factory for additional terminals.

Standard

Type -638	Type -715	Type -700	
1.27mm pitch 	1.00mm pitch 	0.80mm pitch 	

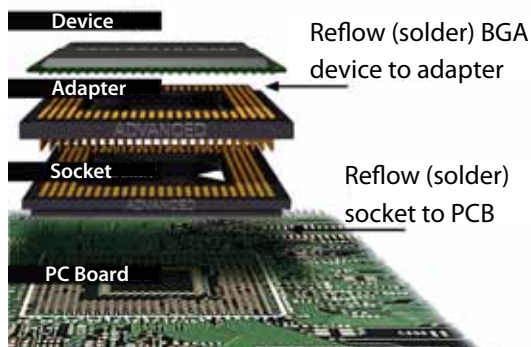
Male to Male

Type -721	Type -735	Type -732	
1.27mm pitch 	1.00mm pitch 	0.80mm pitch 	

SMT (Surface Mount)

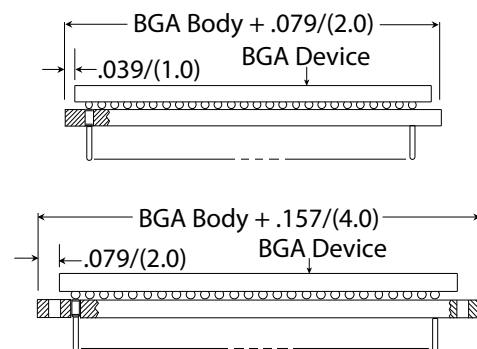
Tin/Lead: Type -720	Tin/Lead: Type -737	Tin/Lead: Type -736	
Lead-free: Type -823	Lead-free: Type -824	Lead-free: Type -829	
1.27mm pitch 	1.00mm pitch 	0.80mm pitch 	

How It Works



- Either Tin/Lead or Lead-free device packages can be attached to our RoHS Compliant Adapters.
- PC boards can be processed with Tin/Lead BGA sockets in standard profiles, or Lead-free BGA sockets in RoHS Compliant, high temperature profiles.
- Generic reflow profiles available online

Dimensional Information



Standard Adapter (A)

- Mates with Standard Socket (S)
- Adapter size equals BGA Device body + .079/(2.00)

Extraction Slot Adapter (AX)

- Slots allow AIC extraction tool (sold separately) to easily remove device/adapter assembly from socket
- Mates with Extraction Socket (SB)
- Adapter size equals BGA Device body + .157/(4.00)

BGA Socket Adapter Systems



Features

- Advanced® exclusive solder ball terminals offer superior SMT processing.
- Same footprint as BGA device.
- Proven long-term performance in vigorous temperature cycling applications - solder ball terminal absorbs TCE mismatch.
- Closed bottom socket terminal for 100% anti-wicking of solder.
- Gold contacts allow gold/gold interconnections to Adapter pins.
- Low insertion force socket with multi-finger high reliability Beryllium Copper contacts.
- Coplanarity consistently better than the .006/(0.152mm) industry standard.
- Custom designs available.

Specifications

Terminals:

Brass - Copper Alloy (C36000)

Contacts:

Beryllium Copper (C17200)

Solder Ball:



Lead-free: 95.5Sn/4.0Ag/0.5Cu
Tin/Lead: 63Sn/37Pb

Plating:

G - Gold over Nickel

Ball Grid Array (BGA) Adapter Sockets 0.80mm, 1.00mm, and 1.27mm Pitch

Table of Models

	Description: Standard Socket (S) Material: High Temp. Liquid Crystal Polymer (LCP)* or FR-4	Insulator Size: Same size as BGA device body
	Description: Extraction Socket (SB) Material: High Temp. Liquid Crystal Polymer (LCP)* or FR-4	Insulator Size: 1.27mm Pitch: BGA device body +.079/(2.00) 1.00mm Pitch: BGA device body +.138/(3.50)

RGS/RGSB replaces MGS/MGSB.

* Some sizes may only be available in FR-4. See How To Order section or consult factory.

Options



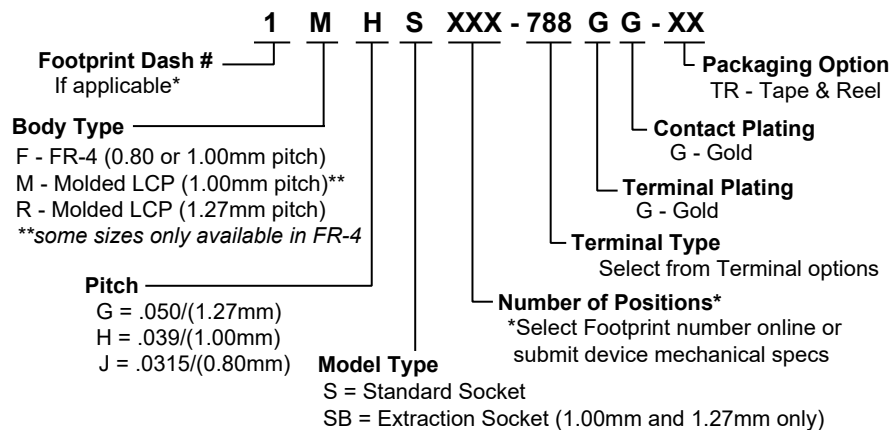
Tape and Reel Packaging

- Conforms to EIA-481 Standard.
- Pick-up tape included.
- Add -TR to end of part number when ordering.
- Custom packaging available.
- If -TR is not specified, standard tray packs are used.

Extraction Tool

- Extraction tool (P/N 8125) is available separately.
- Works with Extraction Slot Adapters.

How To Order



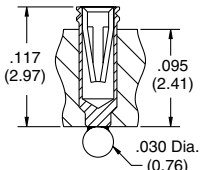
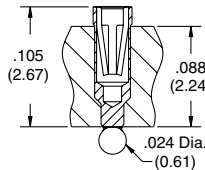
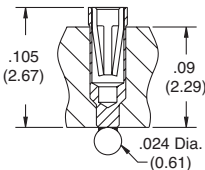
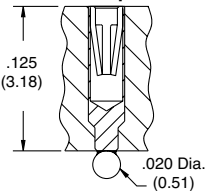
Ball Grid Array (BGA) Adapter Sockets

For use with mating BGA Adapters

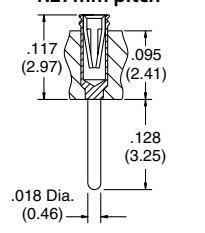
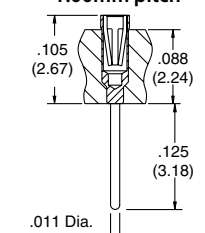
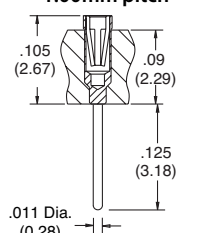
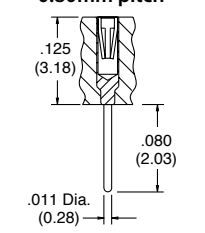
BGA Socket Adapter Systems

Standard Terminals

SMT (Surface Mount)

Tin/Lead: Type -636	Tin/Lead: Type -790	Tin/Lead: Type -716	Tin/Lead: Type -702
Lead-free: Type -819	Lead-free: Type -788	Lead-free: Type -816	Lead-free: Type -828
1.27mm pitch 	1.00mm pitch 	1.00mm pitch 	0.80mm pitch 

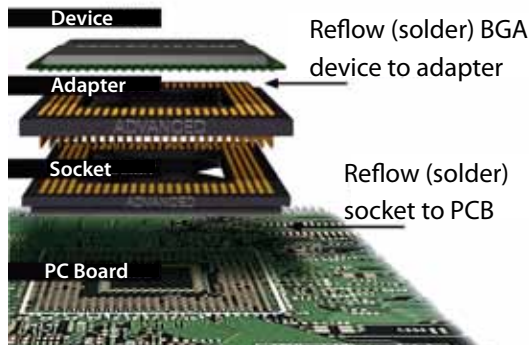
Thru-Hole

Tin/Lead: Type -673	Tin/Lead: Type -789	Tin/Lead: Type -769	Tin/Lead: Type -731
1.27mm pitch 	1.00mm pitch 	1.00mm pitch 	0.80mm pitch 

Additional standard and custom terminals available. See Terminals section or consult factory.

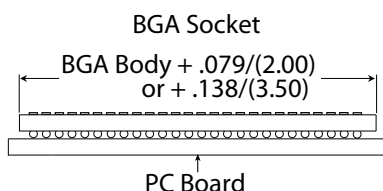
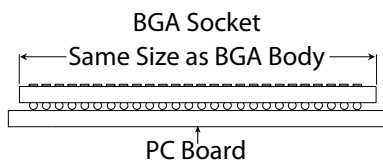
Please consult Sales office for footprint and part number.

How It Works



- Either Tin/Lead or Lead-free device packages can be attached to our RoHS Compliant Adapters.
- PC boards can be processed with Tin/Lead BGA sockets in standard profiles or Lead-free BGA sockets in RoHS Compliant, high temperature profiles.
- Generic Reflow Profiles available online.

Dimensional Information



Standard Adapter (A)

- Mates with Standard Adapter (A)
- Socket size same as BGA device body
- Use with SMT Adapter for LGA and reworked BGA device socketing (or board to board applications)

Extraction Slot (SB)

- Mates with Extraction Slot Adapter (AX)
- Socket size equals BGA body + .079/(2.00) for 1.27mm pitch or BGA body + .138/(3.50) for 1.00mm pitch
- Protects valuable PCB during device/adapter extraction - tool never touches PCB
- Available in 1.00 and 1.27mm pitch only

